



## Material Content Data Sheet



<b>Sales Product Name</b>		BSS83P H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000932464						
<b>Package</b>		PG-SOT23-3-5		<b>Weight*</b>		9.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.008	0.08		811	
	noble metal	gold	7440-57-5	0.029	0.31		3144	
	inorganic material	silicon	7440-21-3	0.166	1.78	2.17	17814	21769
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		971	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		324	
	non noble metal	copper	7440-50-8	3.000	32.22	32.36	322227	323587
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	775	775
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6073	
	plastics	epoxy resin	-	1.216	13.06		130559	
	inorganic material	silicondioxide	60676-86-0	4.382	47.06	60.73	470621	607253
leadfinish	non noble metal	tin	7440-31-5	0.150	1.61	1.61	16071	16071
plating	noble metal	silver	7440-22-4	0.284	3.05	3.05	30545	30545
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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